

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE30P10S uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -30V, I_{D} = -10A$

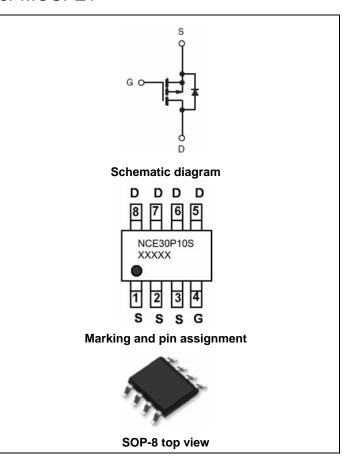
 $R_{DS(ON)}$ < 34m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 21m Ω @ V_{GS} =-10V

- High Power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management



Package Marking and Ordering Information

	<u> </u>				
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30P10S	NCE30P10S	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	-30	V	
Gate-Source Voltage	V _{GS}	±20	V	
Drain Current-Continuous (T _C =25°C)		-10	А	
Drain Current-Continuous (T _C =100℃)	I _D	-7.1		
Drain Current-Pulsed (Note 1)	I _{DM}	-40	Α	
Maximum Power Dissipation (T _C =25°C)	Ъ	3	W	
Maximum Power Dissipation (T _C =100°C)	P _D	1.3] vv	
Single pulse avalanche energy (Note 5)	E _{AS}	231	mJ	
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	41.67	°C/W



Electrical Characteristics (T_A=25 $^{\circ}$ C unless otherwise noted)

Parameter	Parameter Symbol Condition		Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V		-	-1	μΑ
Gate-Body Leakage Current	ody Leakage Current I _{GSS} V _{GS} =±20V,V _{DS} =0V		-	-	±100	nA
On Characteristics (Note 3)	<u> </u>		•		•	
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =-250μA	-1	-1.6	-2.2	V
5 . 6 . 6 . 6 . 7	_	V _{GS} =-10V, I _D =-10A	-	17.6	21	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-10A	-	25.5	34	mΩ
Forward Transconductance	9 FS	V _{DS} =-5V,I _D =-10A	-	20	-	S
Dynamic Characteristics (Note4)	1	1	I	l	I	
Input Capacitance	C _{lss}	15/// 0)/	-	1253	-	PF
Output Capacitance	C _{oss}	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	181	-	PF
Reverse Transfer Capacitance	C_{rss}	F=1.UMMZ	-	158	-	PF
Switching Characteristics (Note 4)	<u> </u>		•		•	
Turn-on Delay Time	$t_{d(on)}$		-	8	-	nS
Turn-on Rise Time	t _r	V _{DD} =-15V, ID=-10A,	-	9	-	nS
Turn-Off Delay Time	$t_{\sf d(off)}$	V_{GS} =-10V, R_{GEN} =1 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	8	-	nS
Total Gate Charge	Qg		-	24.4	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-10A,V _{GS} =-10V	-	3.2	-	nC
Gate-Drain Charge	Q_{gd}	1	-	6.4	-	nC
Drain-Source Diode Characteristics	1		1	1	1	
Diode Forward Current (Note 2)	Is		-	-	-10	Α
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =-10A	-	-	-1.2	V

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E_{AS} condition: Tj=25 $^{\circ}$ C,V_{DD}=-15V,V_G=10V,L=0.5mH,Rg=25 Ω



Typical Electrical and Thermal Characteristics

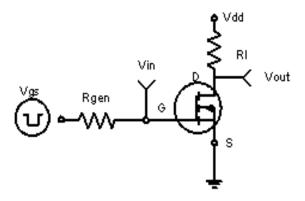


Figure 1:Switching Test Circuit

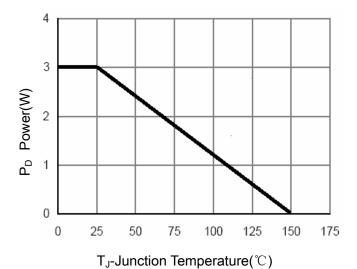


Figure 3 Power Dissipation

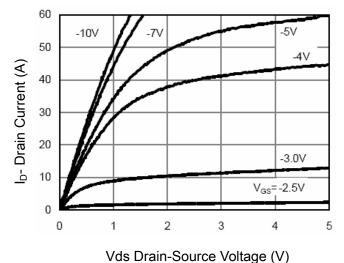


Figure 5 Output Characteristics

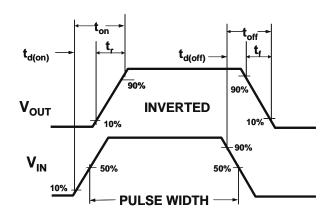


Figure 2:Switching Waveforms

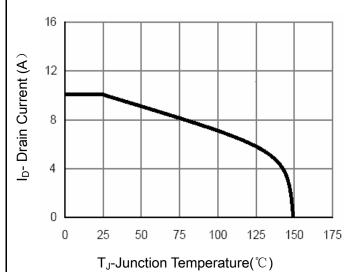


Figure 4 Drain Current

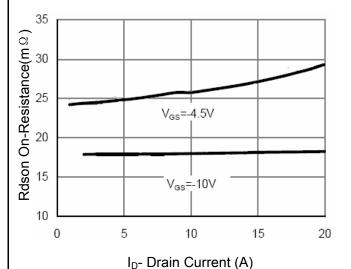
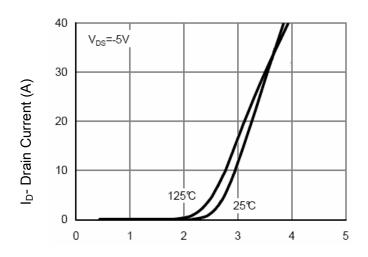
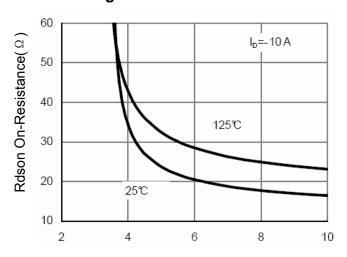


Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

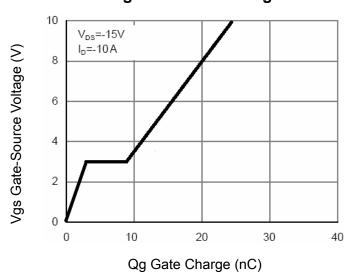


Figure 11 Gate Charge

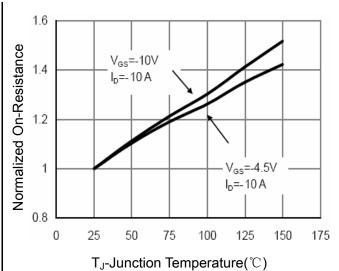


Figure 8 Drain-Source On-Resistance

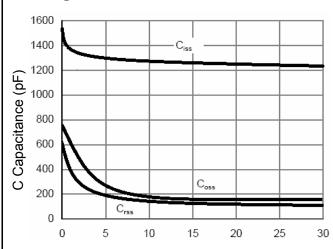


Figure 10 Capacitance vs Vds

Vds Drain-Source Voltage (V)

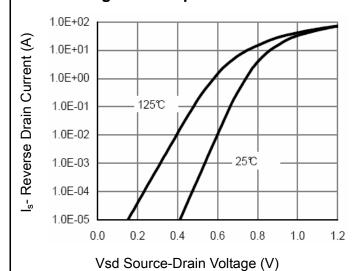


Figure 12 Source- Drain Diode Forward



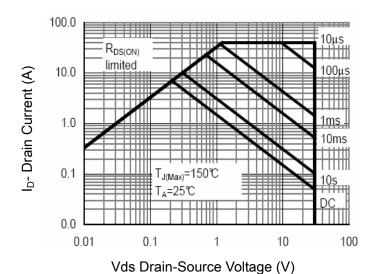


Figure 13 Safe Operation Area

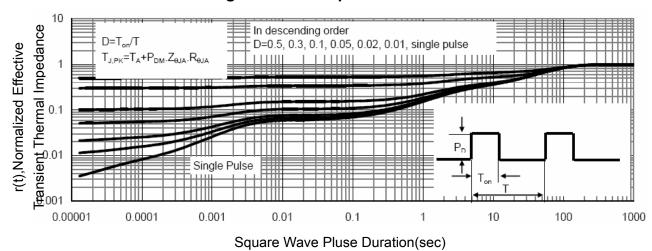
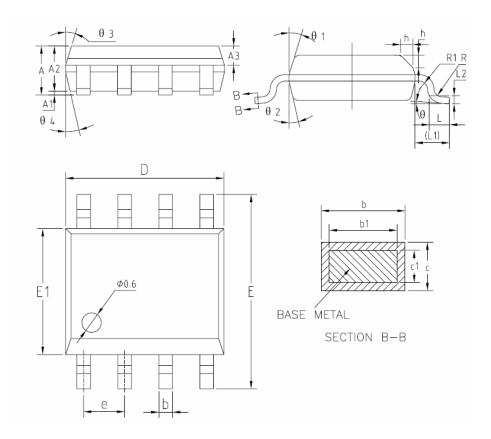


Figure 14 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
Α	1.35	1.55	1.75	
A1	0.10	0.15	0.25	
A2	1.25	1.40	1.65	
A3	0.50	0.60	0.70	
b	0.38	_	0.51	
b1	0.37	0.42	0.47	
С	0.18	-	0.25	
c1	0.17	0.20	0.23	
D E	4.80	4.90	5.00	
E	5.80	6.00	6.20	
E1	3.80	3.90	4.00	
е	1.17	1.27	1.37	
L	0.45	0.60	0.80	
L1	1.04REF			
L2	0.25BSC			
R	0.07	-	_	
R1	0.07	_	_	
h	0.30	0.40	0.50	
θ	0,	_	8°	
θ 1	15°	17°	19*	
θ 2	11*	13°	15"	
θ3	15°	17*	19*	
θ 4	11*	13°	15*	

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